

Arrangement for the Protection of Three-Dimensional Structures on Wafers

ABSTRACT OF THE DISCLOSURE

An electronic component includes a wafer and a number of bond pads disposed on the wafer. A number of functional 3-D structures are disposed on the wafer. Each functional 3-D structure includes a compliant base element. A number of reroute traces are electrically connected to one of the bond pads and extend onto a surface of one of the functional 3-D structures. A number of selected 3-D structures is disposed on the wafer to provide a mechanical reinforcement. At least some of the selected 3-D structures have a greater mechanical load-bearing capacity than some the functional 3-D structures.